

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) An apparatus for selectively applying different amounts of pressure to a plurality of locations on a backside of a substantially circular semiconductor device structure, comprising:

a support structure configured to receive the semiconductor device structure;

a plurality of pressurization rings within saidthe support structure, each of saidthe plurality of pressurization rings being configured to apply pressure to a correspondingly annular region of the backside of the semiconductor device structure assembled with saidthe support structure; and

a plurality of magnetic controllers, each of saidthe plurality of magnetic controllers associated with a corresponding one of saidthe plurality of pressurization rings.

2. (Currently amended) The apparatus of claim 1, wherein each of saidthe plurality of pressurization rings comprises a magnetized material.

3. (Currently amended) The apparatus of claim 2, wherein each of saidthe plurality of magnetic controllers is positioned adjacent saidthe corresponding one of saidthe plurality of pressurization rings and is oriented to repel saidthe corresponding one of saidthe plurality of pressurization rings.

4. (Currently amended) The apparatus of claim 2, wherein each of saidthe plurality of magnetic controllers is positioned opposite the semiconductor device structure assembled with saidthe support structure from saidthe corresponding one of saidthe plurality of pressurization rings and is oriented to attract saidthe corresponding one of saidthe plurality of pressurization rings.

5. (Currently amended) The apparatus of claim 1, wherein each of said~~the~~ the plurality of pressurization rings comprises a material that is attracted to a magnetic field.

6. (Currently amended) The apparatus of claim 5, wherein each of said~~the~~ the plurality of magnetic controllers is located so as to magnetically attract said~~the~~ the corresponding one of said~~the~~ the plurality of pressurization rings.

7. (Currently amended) The apparatus of claim 6, wherein, as at least one pressurization ring of said~~the~~ the plurality of pressurization rings is attracted toward a corresponding one of said~~the~~ the plurality of magnetic controllers, said~~the~~ at least one pressurization ring is configured to be biased against and to apply pressure to the backside of the semiconductor device structure at a corresponding annular region thereof.

8. (Currently amended) The apparatus of claim 5, wherein said~~the~~ the material comprises a ferrous material.

9. (Currently amended) The apparatus of claim 5, wherein said~~the~~ the material comprises a magnetized material.

10. (Currently amended) The apparatus of claim 1, wherein each of said~~the~~ the plurality of magnetic controllers comprises an electromagnet.

11. (Currently amended) The apparatus of claim 1, wherein each of said~~the~~ the plurality of magnetic controllers is configured to be moved toward and away from said~~the~~ the corresponding one of said~~the~~ the plurality of pressurization rings.

12. (Currently amended) The apparatus of claim 1, wherein each of said~~the~~ the plurality of magnetic controllers is configured to bias said~~the~~ the corresponding one of said~~the~~ the plurality of

pressurization rings against corresponding annular regions of the backside of the semiconductor device structure with a variable magnitude of force.

13. (Currently amended) An apparatus for selectively applying different amounts of pressure to a plurality of locations on a backside of a semiconductor device structure, comprising:

a support structure configured to receive the semiconductor device structure;

a plurality of independently movable pressurization structures located within saidthe support structure, each of saidthe pressurization structures located and oriented adjacent a region on a backside of a semiconductor device structure assembled-upon assembly of the semiconductor device structure with saidthe support structure; and

a plurality of actuators, each of saidthe plurality of actuators associated with a corresponding pressurization structure of saidthe plurality of pressurization structures so as to independently bias saidthe corresponding pressurization structure against the backside of the semiconductor device structure assembled with saidthe support structure.

14. (Currently amended) The apparatus of claim 13, wherein each of saidthe plurality of pressurization structures comprises a ring.

15. (Currently amended) The apparatus of claim 13, wherein each of saidthe plurality of actuators comprises a magnetic controller.

16. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of pressurization structures comprises a magnetized material.

17. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of pressurization structures comprises a material that is attracted to a magnetic field.

18. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators is oriented so as to repel a corresponding pressurization structure.

19. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators is oriented so as to attract a corresponding pressurization structure.

20. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators comprises an electromagnet.

21. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators is movable toward and away from a corresponding pressurization structure.

22. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators comprises a vacuum source.

23. (Currently amended) The apparatus of claim 22, further comprising a spring associated with each of saidthe plurality of independently movable pressurization structures, each saidthe spring biasing a corresponding pressurization structure against the backside of the semiconductor device structure, each of saidthe plurality of actuators being configured to pull a corresponding one of saidthe plurality of independently movable pressurization structures away from the backside of the semiconductor device structure.

24. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators comprises a positive pressure source.

25. (Currently amended) The apparatus of claim 24, further comprising a spring associated with each of saidthe plurality of independently movable pressurization structures.

26. (Currently amended) The apparatus of claim 24, wherein saidthe positive pressure source is configured to bias a corresponding pressurization structure against the backside of the semiconductor device structure assembled with saidthe support structure.

27. (Currently amended) The apparatus of claim 15, wherein each of saidthe plurality of actuators is configured to bias saidthe corresponding pressurization structure against the backside of the semiconductor device structure assembled with saidthe support structure with variable amounts of force.

28. (Currently amended) The apparatus of claim 18, wherein each of saidthe plurality of actuators is located to force saidthe corresponding pressurization structure against the backside of the semiconductor device structure assembled with saidthe support structure.

29. (Currently amended) The apparatus of claim 19, wherein each of saidthe plurality of actuators is located to pull saidthe corresponding pressurization structure against the backside of the semiconductor device structure assembled with saidthe support structure.

30. (Currently amended) The apparatus of claim 15, wherein each of saidthe of pressurization structures has associated therewith a spring.

31-94 (Canceled)